



# Koruza-CM

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- PAGE4 - SFP

## Version Revision:

- v0.2 - 09.03.2017.
- v0.3 - 30.03.2017.
- v0.3.1 - 05.05.2017.

## DESIGN CONSIDERATIONS

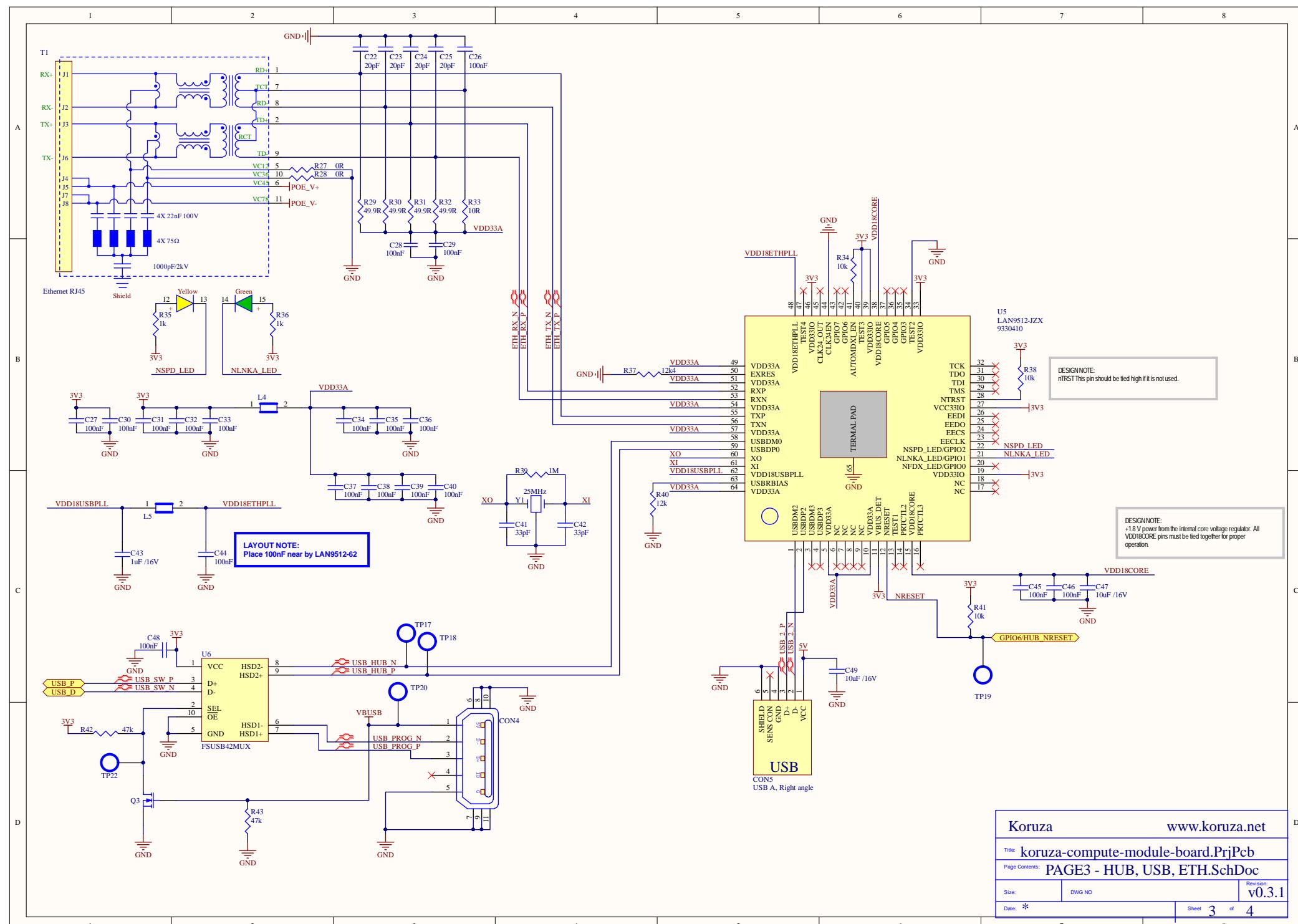
**DESIGN NOTE:**  
Example text for informational design notes.

**DESIGN NOTE:**  
Example text for critical design notes.

**LAYOUT NOTE:**  
Example text for critical layout guidelines.

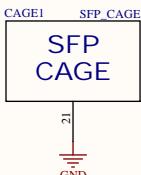
Koruza		www.koruza.net
Title: koruza-compute-module-board.PrjPcb		
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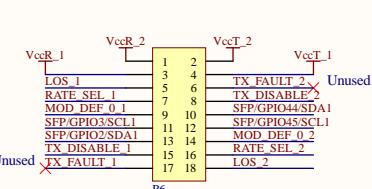


# Rigid to Flex PCB connection

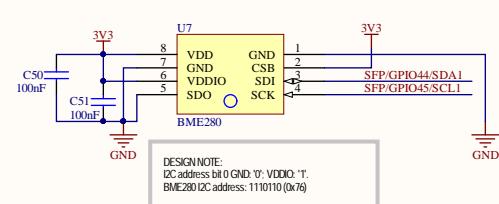
SFP Cage Rigid to flex connector



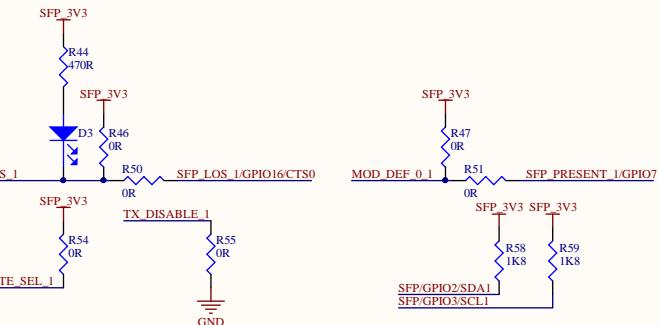
Koruza SFP rigid to flex GPIO connector



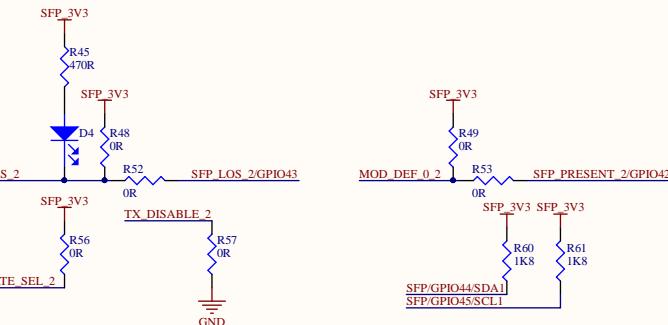
Environment sensor  
Temperature, humidity, pressure



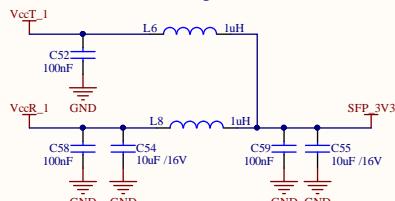
SFP1 GPIO config



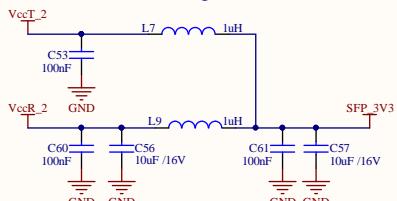
SFP2 GPIO config



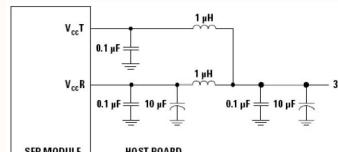
SFP1 Power filtering network



SFP2 Power filtering network



DESIGN NOTE:  
Note: Inductors with DC resistance of less than 1Ω should be used in order to prevent the required voltage at the SFP module pin at 3.3V. When the required supply filtering circuit is used, hot plugging of the SFP transceiver module will result in an initial current of no more than 30 mA greater than the steady state value.



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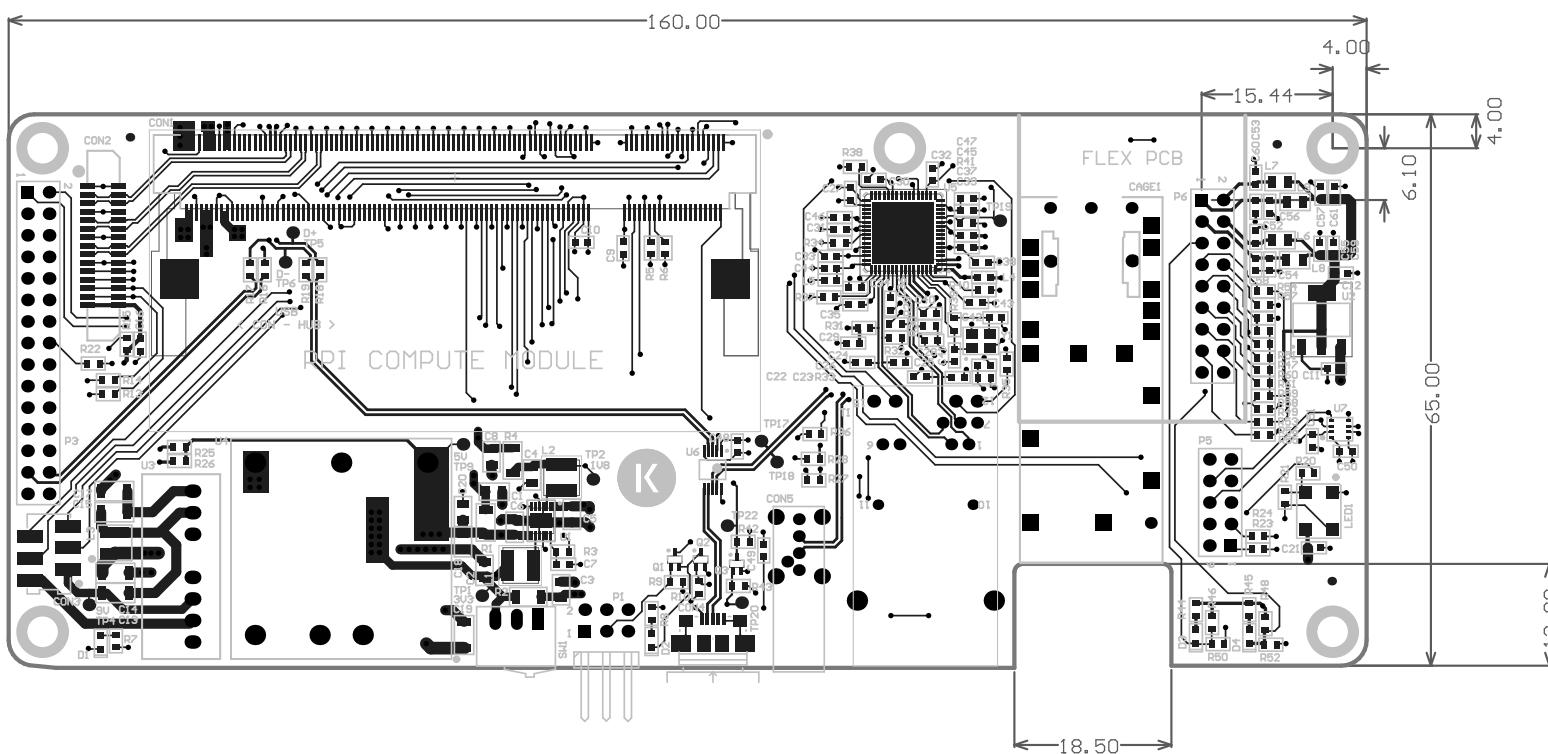
Title: koruza-compute-module-board.PrjPcb

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Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.040mm		
4	Dielectric 1	FR-4	0.240mm	4.6	
5	Ground Plane	Copper	0.035mm		
6	Dielectric 3	R-1755M	0.400mm	4.6	
7	Power Plane	Copper	0.035mm		
8	Dielectric 4		0.254mm	4.2	
9	Solder Side	Copper	0.040mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				



Layer	Name	Material	Count	Layer Stackup	Trilayer Stackup	Coupling Factor
1	Top Overlay					
2	Top Solder	Solder Resist	0.010mm	3.B		
3	Couplingout Side	Copper	0.040mm			
4	Dielectric 1	FR-4	0.240mm	4.B		
5	Grounnd Plane	Copper	0.035mm			
6	Dielectric 3	FR-4	0.400mm	4.B		
7	Power Plane	Copper	0.035mm			
8	Dielectric 4	FR-4	0.254mm	4.C		
9	Solder Side	Copper	0.040mm			
10	Bottom Overlay	Solder Resist	0.010mm	3.B		
11	Bottom Overlay					

